

#### Description

The AOD4130-HXY uses advanced trench technology

to provide excellent  $R_{\text{DS}(\text{ON})},$  low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

### **General Features**

 $V_{DS} = 60V I_D = 30 A$ 

 $R_{DS(ON)} < 26m\Omega @ V_{GS}=10V$ 

### Application

Battery protection

Load switch

Uninterruptible power supply

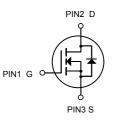
#### Package Marking and Ordering Information

Due du et ID	Deals	Marking Ofu (DOO)		
Product ID	Pack	Marking	Qty(PCS)	
AOD4130-HXY	TO252-2L	30N06XXXX YYYY	2500	

### Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	60	V
Vgs	Gate-Source Voltage	±20	V
I⊳@Tc=25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	30	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	15	А
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5.6	А
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	4.5	А
Ідм	Pulsed Drain Current <sup>2</sup>	46	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	25.5	mJ
las	Avalanche Current	22.6	А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	34.7	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	2	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C





N-Channel MOSFET



AOD4130-HXY

N-Channel Enhancement Mode MOSFET

Reja	Thermal Resistance Ju	Thermal Resistance Junction-Ambient <sup>1</sup>		62		°C/W	
Rejc Thermal Resistan		Junction-Case <sup>1</sup>	3.6		°C/W		
ectrical C	Characteristics (TJ=25 °C, unle	ss otherwise noted)					
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60			V	
∆BV <sub>DSS</sub> /∆TJ	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C,I <sub>D</sub> =1mA		0.063		V/°C	
		V <sub>GS</sub> =10V , I <sub>D</sub> =15A		22	26		
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		30	38	mΩ	
VGS(th)	Gate Threshold Voltage		1.2		2.5	V	
$\bigtriangleup V_{\text{GS(th)}}$	V <sub>GS(th)</sub> Temperature Coefficient	—V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA		-5.24		mV/°	
		V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1		
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA	
lgss	Gate-Source Leakage Current	$V_{GS}$ =±20V , $V_{DS}$ =0V			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =15A		17		S	
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		3.2		Ω	
Qg	Total Gate Charge (4.5V)			12.6		nC	
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =48V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =12A		3.2			
$Q_{gd}$	Gate-Drain Charge	_		6.3			
Td(on)	Turn-On Delay Time			8			
Tr	Rise Time	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V ,		14.2		ns	
Td(off)	Turn-Off Delay Time	—R <sub>G</sub> =3.3 , I <sub>D</sub> =10A		24.4			
T <sub>f</sub>	Fall Time			4.6			
Ciss	Input Capacitance			1378			
Coss	Output Capacitance			86		pF	
Crss	Reverse Transfer Capacitance			64			
ls	Continuous Source Current <sup>1,5</sup>				23	A	
lsм	Pulsed Source Current <sup>2,5</sup>	$-V_G=V_D=0V$ , Force Current			46	A	
Vsd	Diode Forward Voltage <sup>2</sup>				1.2	V	

Note :

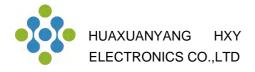
1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\leqq$  300us , duty cycle  $\leqq$  2%

3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=22.6A

4.The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



## AOD4130-HXY N-Channel Enhancement Mode MOSFET

### **Typical Characteristics**

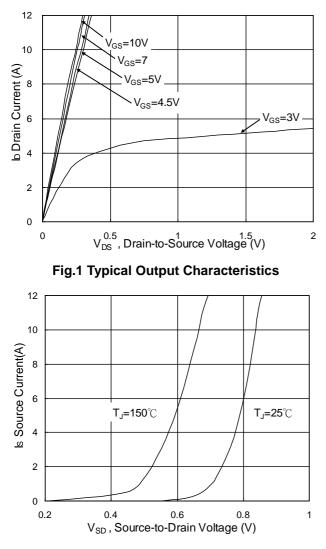


Fig.3 Forward Characteristics of Reverse

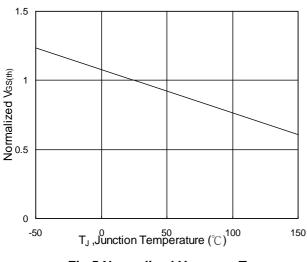


Fig.5 Normalized  $V_{GS(th)}$  v.s T<sub>J</sub>

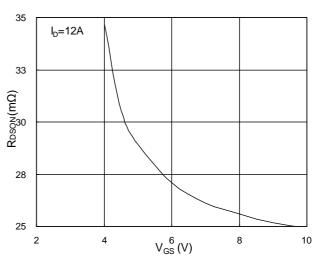


Fig.2 On-Resistance v.s Gate-Source

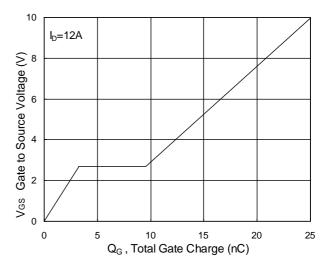


Fig.4 Gate-Charge Characteristics

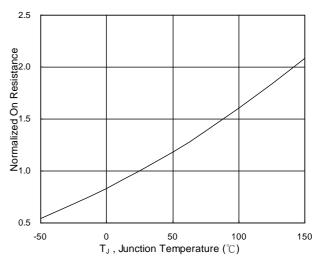


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>



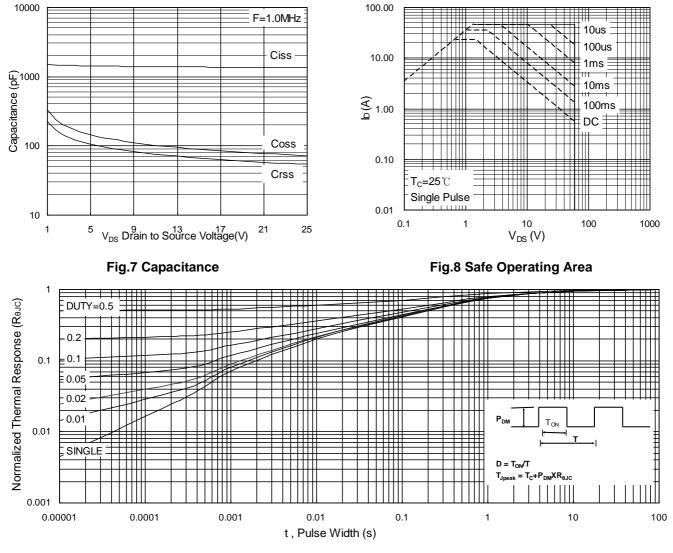


Fig.9 Normalized Maximum Transient Thermal Impedance

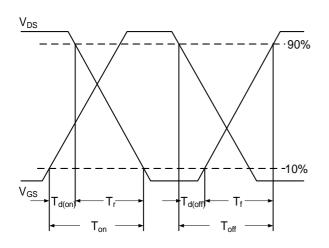
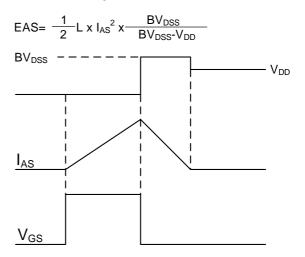
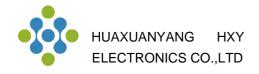


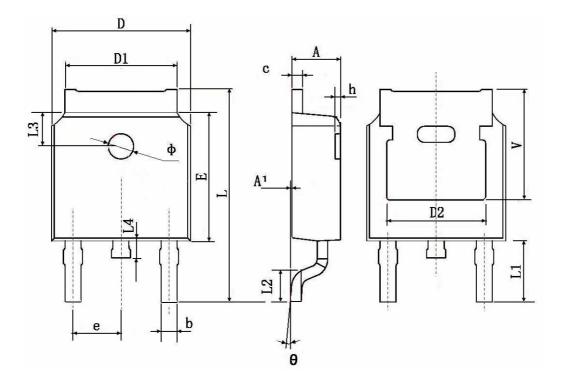
Fig.10 Switching Time Waveform







# TO252-2L Package Information



	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483	0.483 TYP.		) TYP.	
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114	TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063	0.063 TYP.	
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0 °	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		



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